



Design. Create. Certify. *Connect.*

---

February 24, 2015

Re: Internal Photos of the TiWi-C-W Module

FCC ID: TFB-1001

IC ID: 5969A-1001

To Whom It May Concern,

LSR does not have internal photos of the TiWi-C-W Module, as the modules are manufactured using a SIP (System In Package) process. This process results in the final modules being encapsulated in the packaging material during time of manufacture. Based on this we are unable to provide pictures of the module without the cover.

Sincerely,

A handwritten signature in black ink, appearing to read 'Bill Steinike', with a long horizontal flourish extending to the right.

William Steinike  
President, LS Research